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Serial No.: Not yet assigned

Filed: Herewith

For: WIRING SUBSTRATE, METHOD OF MANUFACTURING THE SAME
AND SEMICONDUCTOR DEVICE

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M. P. Ridges

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
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Sir:

In the interest of full disclosure, the following items are herewith identified in Form PTO-1449 and a copy of the same is hereby provided, for the convenience of the U.S. Patent and Trademark Office.

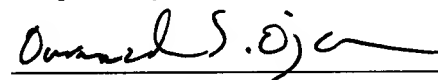
This Information Disclosure Statement is being filed before the mailing date of the first official action.

FOREIGN PATENTS

(AA) **JP-5-47842** Miyamoto Toshio, dated February 26, 1993. For relevance see English abstract.

(AB) **JP-10-270496** Imasu Seishi, dated October 9, 1998. For relevance see English abstract.

Respectfully submitted,



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FOREIGN PATENT DOCUMENTS

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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER**DATE CONSIDERED**

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